FOR IMMEDIATE RELEASE

Empower RF Systems patent approval -
“RF Power Amplifier and Method of Assembly for Same”

United States Patent 9,007,125 B2, recently awarded to Empower RF Systems, validates the uniqueness of the hardware architecture in use on Empower’s high power, next generation amplifiers. The ability to deliver 1 kW CW broadband power in an air cooled, 5U chassis (and other combinations of power and chassis sizes utilizing this architecture) requires innovation and engineering breakthroughs that are described and protected in this patent award. “We are pleased to receive this recognition and patent protection for our next generation amplifiers” said Jon Jacocks, CEO. “The hard work and creativity of our design teams, leveraging this architecture for standard products and customer configurations, continues to yield impressive power density and power delivery results”.

The patent was submitted and authored for Empower RF Systems by Paulo Correa, Don Wike, and Leo Mogilevsky. In the approved abstract released by the U.S. Patent & Trademark Office, the patent describes motherboard and heatsink embodiments (and other design elements) which are integral and unique to the high power amplifier, hardware architecture.

An example of this patent protected hardware architecture will be on display and running in a live demo at the upcoming IMS show in Phoenix, AZ - May 19 – 21, 2015, Booth 3226.


Empower RF Systems is a leader in power amplifier solutions for defense, commercial, and industrial applications. Our products incorporate the latest semiconductor and power combining technologies and originate from an extensive library of “building block” designs. Solutions range from basic PA modules to multifunction PA assemblies with embedded, microprocessor controllers.

Visit Empower RF website:
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